IB-WAFER FEEDER

Large-area panel bonding for panel sizes up to 510 × 510 mm, extendable up to 610 × 610 mm

Increase UPH trough parallel processing

INFOTECH automation

INFOTECH ADVANCED PACKAGING

Advanced Packaging for next-generation semiconductor assembly

Enabling higher precision, greater integration, and improved electrical and thermal performance, from lead frames and substrates to wafers and panels.

Infotech provides scalable, high-accuracy solutions for die attach, flip-chip bonding and advanced joining processes, including processes in inert-gas environments. Integrated dispensing, AI vision inspection, testing and underfill modules enable complete, high-throughput production lines.

- **Large-area panel bonding up to 610 × 610 mm**
- **Scalable platform for next-generation packaging and higher throughput**
- **Increase UPH through parallel material feeding and processing**
- **FOUP magazine support**

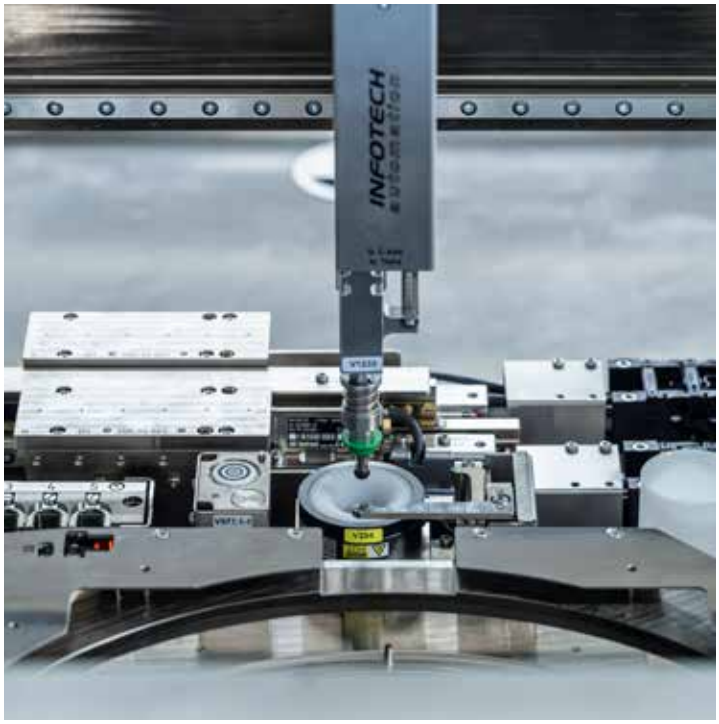
Parallelization

IB-Wafer Feeder with adjustable transport system

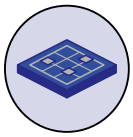
Parallel processing rather than sequential handling, with an extendable conveyor range to a depth of up to 610 mm.

The Infotech IB-Wafer Feeder delivers reliable, automated handling and continuous die supply to keep your bonding process running efficiently.

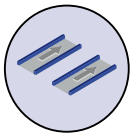
Supporting large panels, it combines stable loading and unloading of dies with precise positioning for high-throughput, repeatable production while reducing operator effort and downtime.



Panel size
HANDLING & TRAVEL RANGE



Parallel
FEEDING & PROCESSING



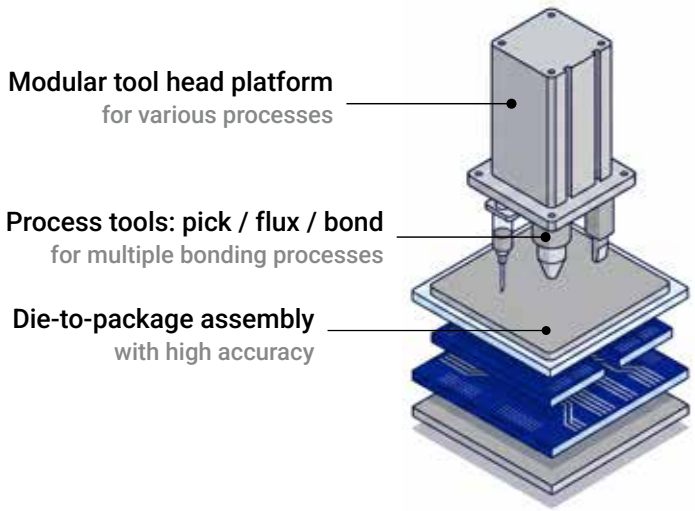
Die Assembly

Advanced Packaging Automation

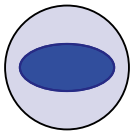
From die to package with automated assembly.

Infotech's modular assembly platform combines flexible process modules with high-precision die handling. It supports a broad range of advanced packaging workflows, from chip-to-wafer and chip-to-substrate to large-die assembly.

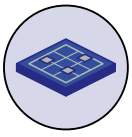
Dispensing · Flip-chip die attach · Sinter bonding
Diffusion bonding · Lid attach · Ultrasonic welding
Pin attach · KGD testing · Large-die handling



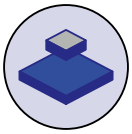
C2W
CHIP-TO-WAFER



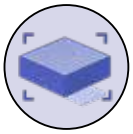
CoP
CHIP-ON-PANEL



C2S
CHIP-TO-SUBSTRATE



Large Die
HANDLING



www.infotech-automation.com
info@infotech.swiss
Tel. +41 32 626 86 00

Technologiestrasse 1
2540 Grenchen
Switzerland

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